

Performance of NiPdAu Products After Long Term Storage

镍钯金产品长期存储后的可靠性评估

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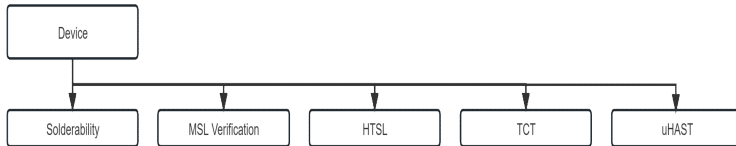
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1. Device Sample 用于评估的样品信息

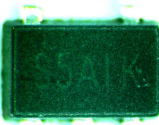
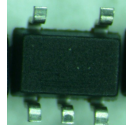
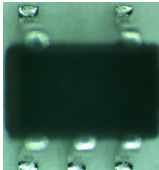
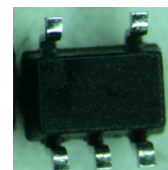
P/N: SGM8701YC5G/TR
 PKG: SC70-5
 Plating: NiPdAu
 MSL: Level 1
 Lot#: B3H377.1E
 D/C: 1846N
 Qty: 1 reels
 Storage: Vacuum MBB seal 铝箔袋真空包装

2. Risk Assessment 风险评估

2.1 Assessment Flow 评估流程



2.2 Assessment for Device 产品的风险评估

Assessment 评估内容	Inspection Result 检测结果
<p>Long term storage products with pure tin finish lead may oxidize the lead surface. 长期存储的产品可能会发生变色、氧化等造成后端 SMT 焊接过程有焊不上、虚焊等焊接异常。</p>	<p>Lead finish would be detected by visual inspection. 引脚镀层的质量可以通过外观检验进行确认：以下超出5年的产品，其引脚镀层正常，未发现氧化、变色等情况。</p> <div style="display: flex; justify-content: space-around;">   </div> <p style="display: flex; justify-content: space-around;"> Top view Bottom view </p>
<p>Solderability verification needed since long term storage products which the lead surface may impact solder wetting during SMT 易焊性测试评估超长存储的产品,其引脚镀层是否影响SMT焊接贴片 Test condition: 245°C@5seconds after bake 4hrs Test sample: 22 leads Criteria: coverage > 95%</p>	<p>Lead finish under solderability test could be detected by visual inspection. 易焊性验证的结果可以通过外观检验进行确认：以下超出5年的产品，易焊性验证合格，覆盖率达95%以上。</p> <div style="display: flex; justify-content: space-around;">   </div> <p style="display: flex; justify-content: space-around;"> Top view Bottom view </p>
<p>Device functionality and parametric performance 产品各项功能参数指标是否符合要求</p>	<p>All devices passed electrical test. 所有测试的产品，其各项功能参数指标均符合规格要求。</p>



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<p>Long term storage products were evaluated with standard JEDEC MSL specification test. 超长存储的产品按照JEDEC标准考核MSL的性能</p>	<p>All devices passed electrical test after TCT qualification 所有经过MSL考核的产品,其各项功能参数指标均合格,符合规格要求。</p>
<p>High Temperature Storage Life Test (HTSL) 高温存储试验 Test condition: 150°C@1000hrs Test sample: 77pcs Criteria: Ac/Rej = 0/1 通过高温存储试验,确认超长存储期产品的各项性能参数指标是否符合要求 (所有样片均经过预处理MSL确认)</p>	<p>All devices passed electrical test after HTSL qualification 所有经过HTSL考核的产品,其各项功能参数指标均合格,符合规格要求。 HTOL qualification data provides the best estimate of parametric performance over time. Devices are biased during HTOL testing – This is worse case compared to unbiased storage. (Calculated the product operation life is over 10 years) HTOL (产品量产初期阶段考核项目)的结果是评估产品寿命最佳的依据。HTOL是带偏压的考核项目,考核周期1008小时,其条件比不带偏压的HTSL更苛刻。正常作业条件下的作业寿命远超10年。</p>
<p>Temperature Cycling Test (TCT) 温度循环试验 Test condition: -65 ~ 150 °C@500 cycles Test sample: 77pcs Criteria: Ac/Rej = 0/1 通过温度循环试验,确认超长存储产品的各项性能参数是否符合要求。 (所有样片均经过预处理MSL确认)</p>	<p>All devices passed electrical test after TCT qualification 所有经过TCT考核的产品,其各项功能参数指标均合格,符合规格要求。</p>
<p>Unbiased Highly Accelerated Temperature & Humidity Stress Test (uHAST) 无偏压高加速应力试验 Test condition: 130°C, 85%RH, 33.3psia@96hrs Test sample: 77pcs Criteria: Ac/Rej = 0/1 通过无偏压高加速应力试验,确认超长存储产品的各项性能参数是否符合要求。 (所有样片均经过预处理MSL确认)</p>	<p>All devices passed electrical test after uHAST qualification 所有经过uHAST考核的产品,其各项功能参数指标均合格,符合规格要求。</p>

2.3 SUMMARY OF RESULTS 考核结果概述

- Device assessment result: MSL1等级产品的评估结果
- 超长存储产品,在包装完好的情况下,其引脚镀层正常,未发现氧化、变色等情况。
- 超长存储产品,易焊性验证合格,焊料覆盖率达95%以上;
- 超长存储产品,测试验证合格,其各项功能参数指标均符合规格要求;
- 超长存储产品,所有经过MSL考核的产品,其各项功能参数指标均合格,符合规格要求;
- 超长存储产品,经过HTSL考核验证,其各项功能参数指标均合格,符合规格要求;
- 超长存储产品,经过TCT考核验证,其各项功能参数指标均合格,符合规格要求;
- 超长存储产品,经过uHAST考核验证,,其各项功能参数指标均合格,符合规格要求。

备注: HTOL (产品量产初期阶段考核项目)的结果是评估产品寿命最佳的依据。HTOL是带偏压的考核项目,考核周期1008小时,其条件比不带偏压的HTSL更苛刻。正常作业条件下的作业寿命远超10年。

2.4 Conclusion 结论

The shelf life of NiPdAu Products determined by optical microscopy, MSL performance, solderability and reliability verification is over 5 years.

圣邦通过对超长存储产品的产品的外观、易焊性、MSL等级确认，以及产品的可靠性评估结果表明，镍钯金产品在包装完好的情况下，存储周期可以达到5年以上，产品性能不变。

3. Relative Documents 参考文件

JEDEC: "J-STD-033 handling, packing, shipping and use of moisture/reflow sensitive surface mount devices"

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